



US009041129B2

(12) **United States Patent**
Ho et al.

(10) **Patent No.:** **US 9,041,129 B2**
(45) **Date of Patent:** **May 26, 2015**

(54) **SEMICONDUCTOR MEMORY STORAGE ARRAY DEVICE AND METHOD FOR FABRICATING THE SAME**

(58) **Field of Classification Search**
USPC 257/4, 43, 421, 5; 438/129, 237, 295, 438/652, 3
See application file for complete search history.

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

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(21) Appl. No.: **14/087,355**

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(22) Filed: **Nov. 22, 2013**

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(65) **Prior Publication Data**

US 2014/0077150 A1 Mar. 20, 2014

Related U.S. Application Data

(63) Continuation-in-part of application No. 13/452,544, filed on Apr. 20, 2012, now Pat. No. 8,835,894.

Primary Examiner — Errol Fernandes

(74) *Attorney, Agent, or Firm* — WPAT, PC; Justin King

(30) **Foreign Application Priority Data**

Feb. 24, 2012 (TW) 101106428 A

(57) **ABSTRACT**

(51) **Int. Cl.**

H01L 29/82 (2006.01)
H01L 27/24 (2006.01)
H01L 27/22 (2006.01)

(Continued)

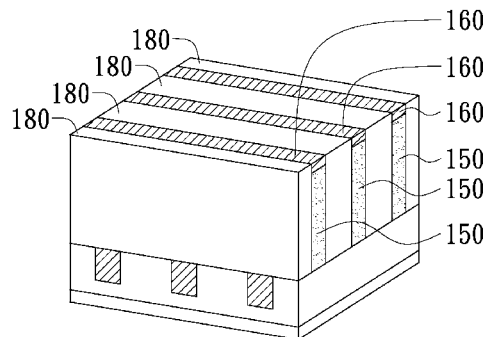
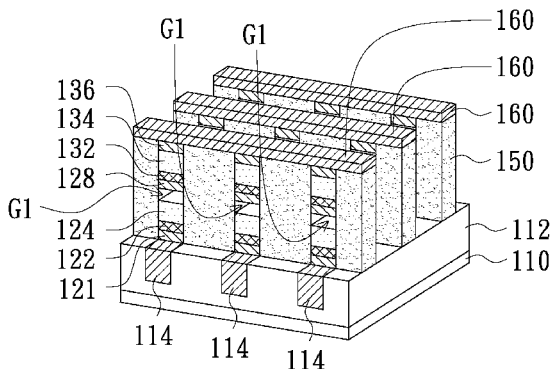
A semiconductor memory storage array device comprises a first electrode layer, an oxide layer, a second electrode layer, a memory material layer and a first insulator layer. The oxide layer is disposed on the first electrode layer. The second electrode layer is disposed on the oxide layer. The memory material layer is disposed on the second electrode layer. The first insulator layer is disposed adjacent to two sidewalls of the first electrode layer, the oxide layer, the second electrode layer and the memory material layer, so to define a gap either between the first electrode layer and the oxide layer or between the second electrode layer and the oxide layer.

(52) **U.S. Cl.**

CPC **H01L 27/2463** (2013.01); **H01L 27/222** (2013.01); **H01L 27/1052** (2013.01); **H01L 45/04** (2013.01); **H01L 45/1233** (2013.01);

(Continued)

7 Claims, 22 Drawing Sheets



- (51) **Int. Cl.**
H01L 27/105 (2006.01)
H01L 45/00 (2006.01)
- (52) **U.S. Cl.**
CPC *H01L 45/1675* (2013.01); *H01L 27/2481*
(2013.01)

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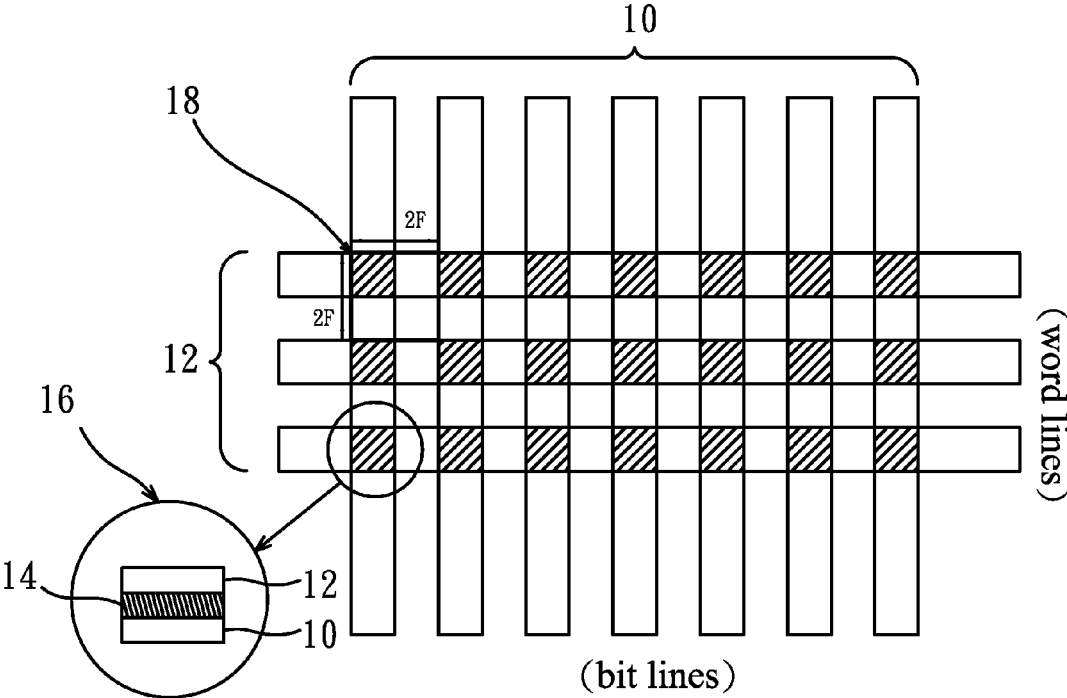


Fig. 1(PRIOR ART)

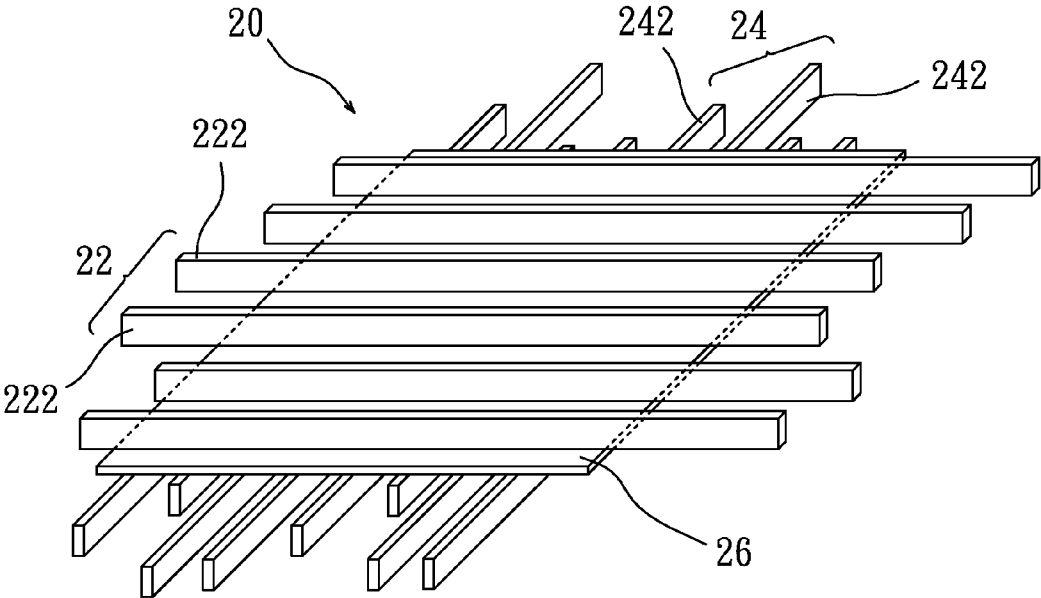


Fig. 2

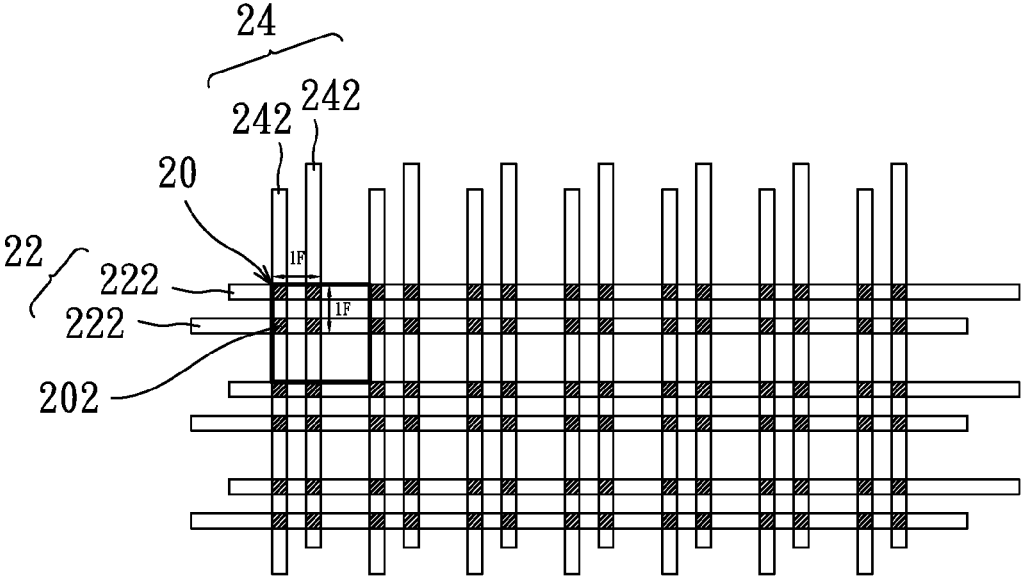


Fig. 3

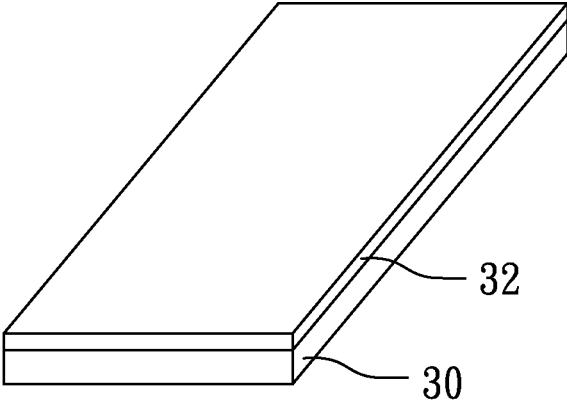


Fig. 4A

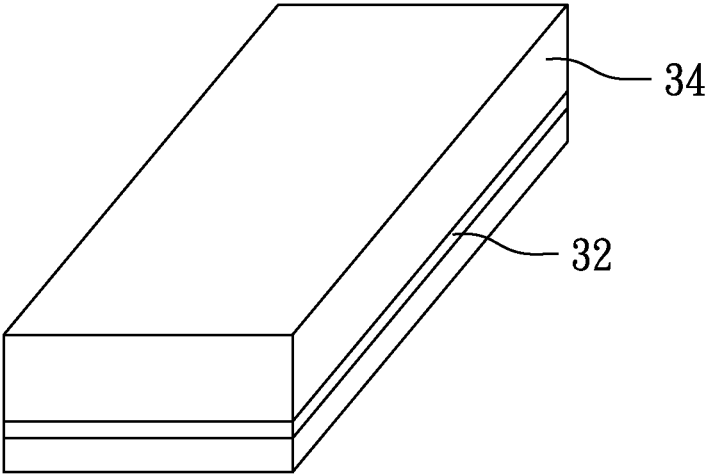


Fig. 4B

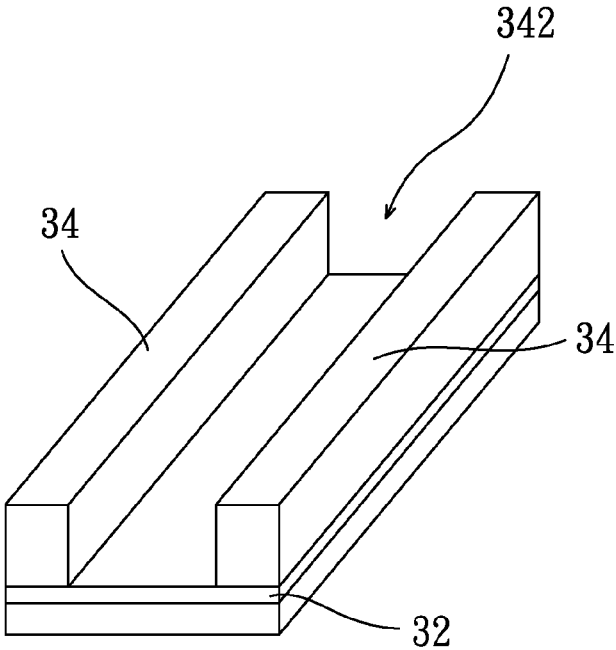


Fig. 4C

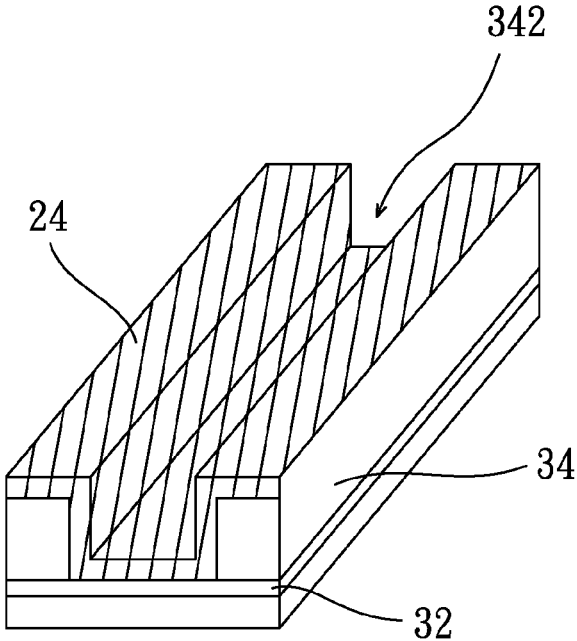


Fig. 4D

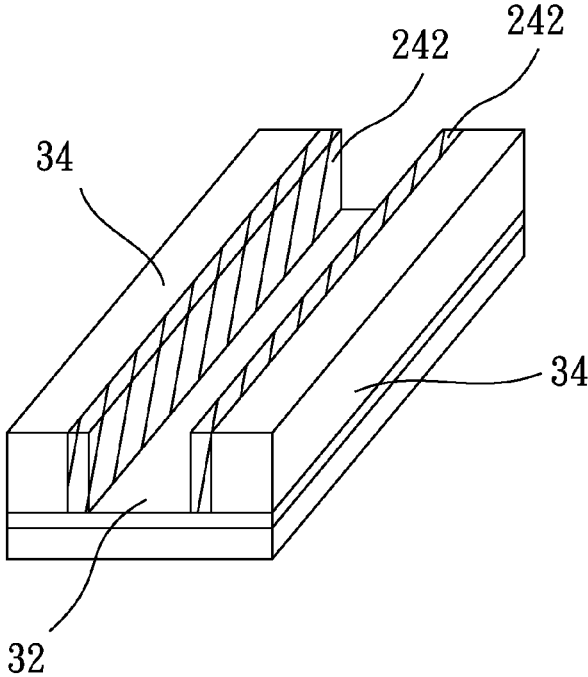


Fig. 4E

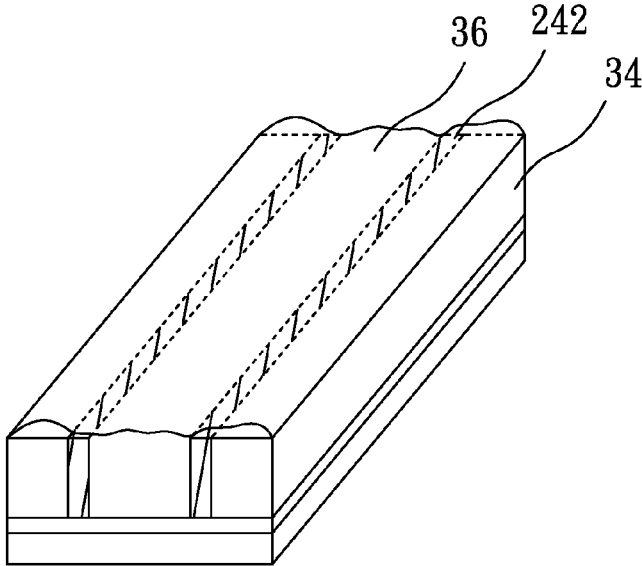


Fig. 4F

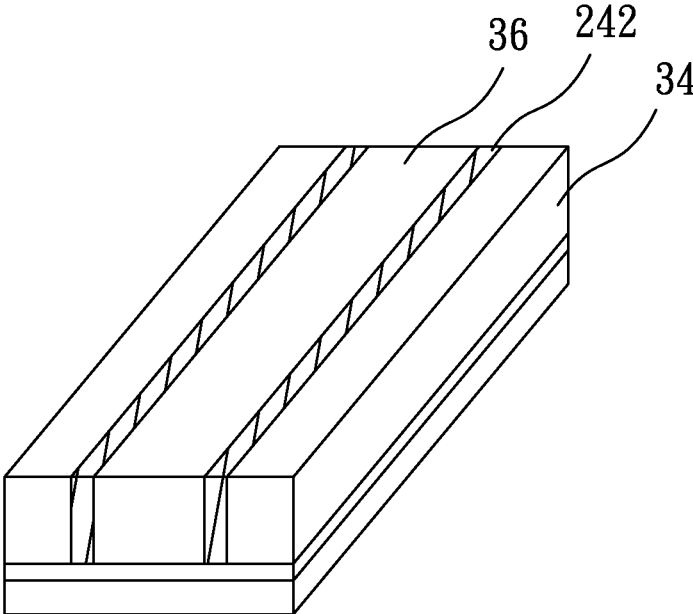


Fig. 4G

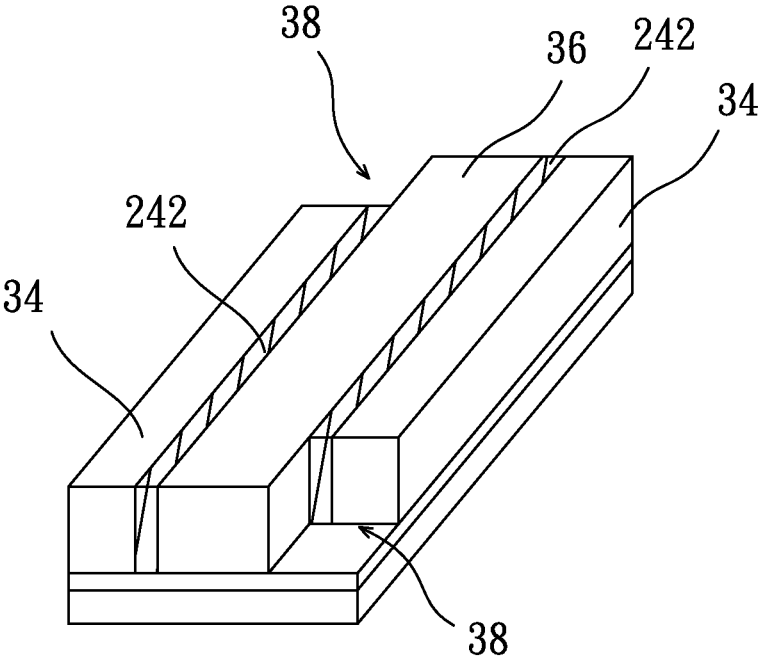


Fig. 4H

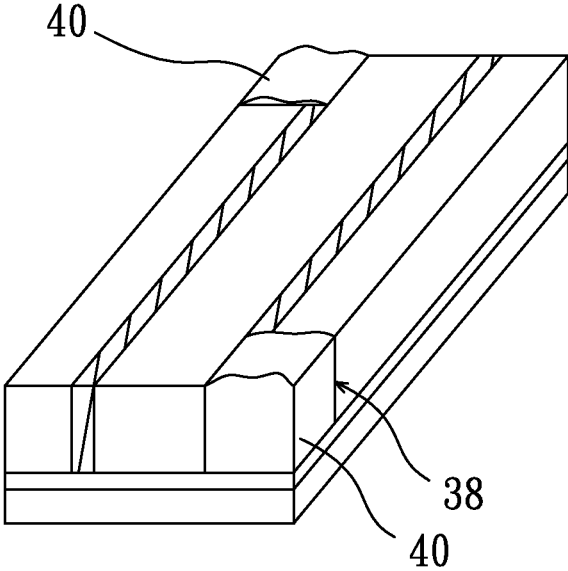


Fig. 4I

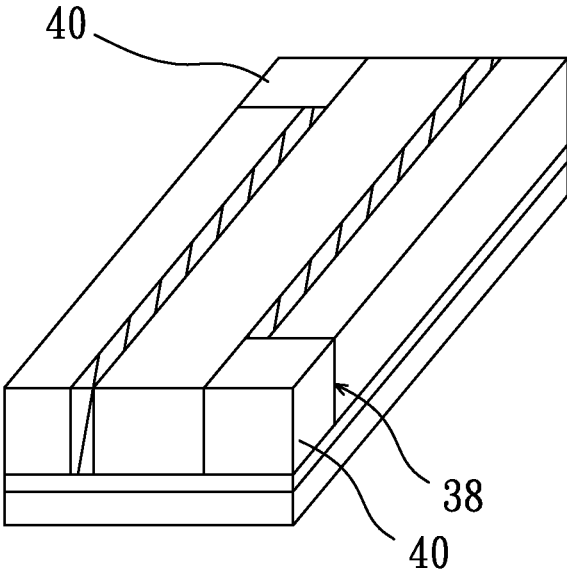


Fig. 4J

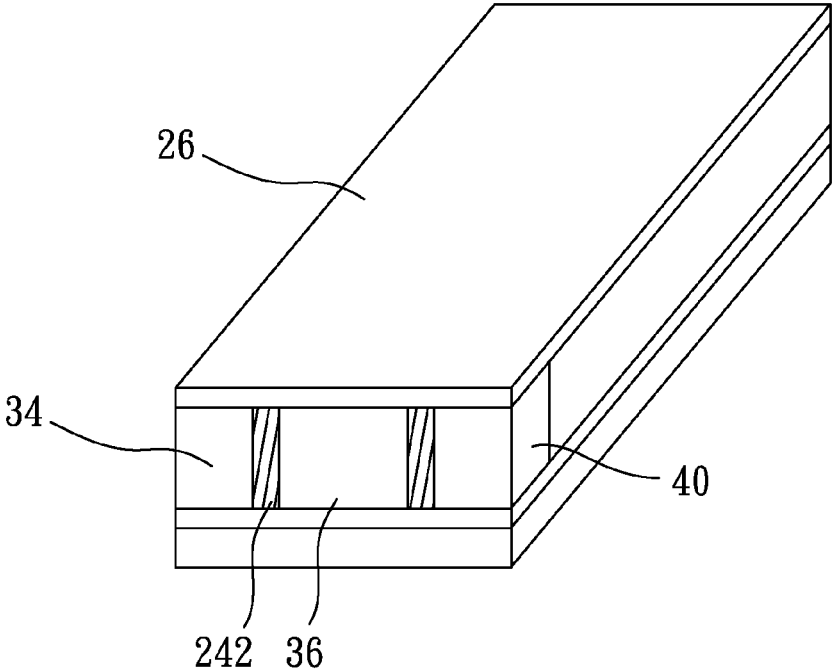


Fig. 4K

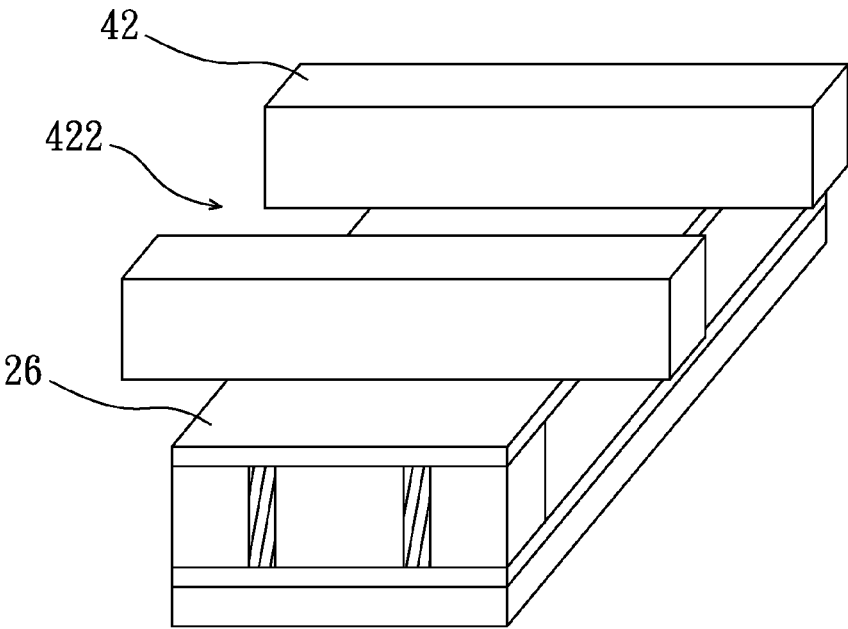


Fig. 4L

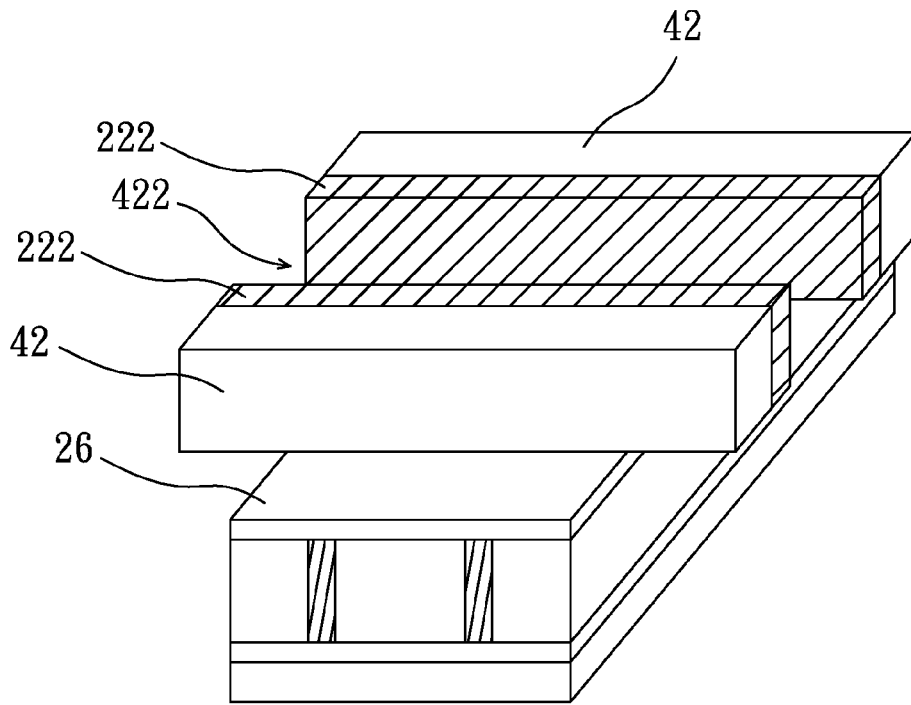


Fig. 4M

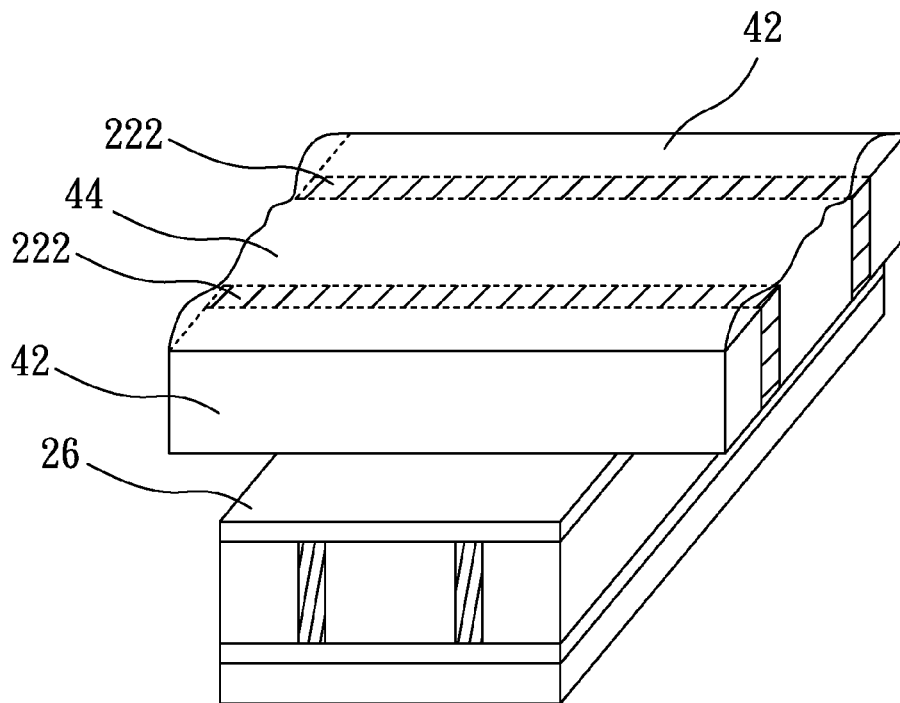


Fig. 4N

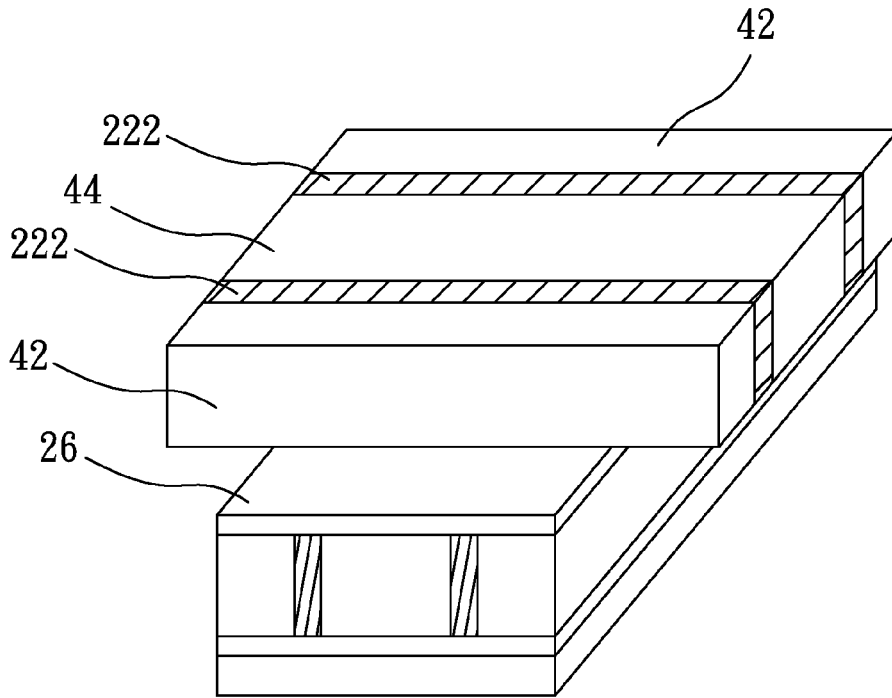


Fig. 40

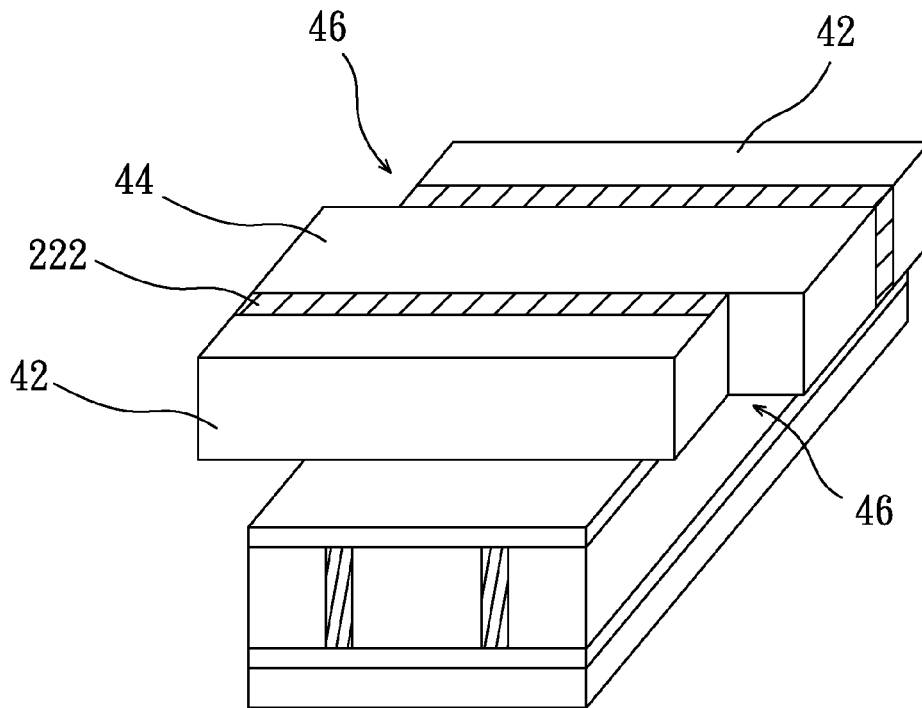


Fig. 4P

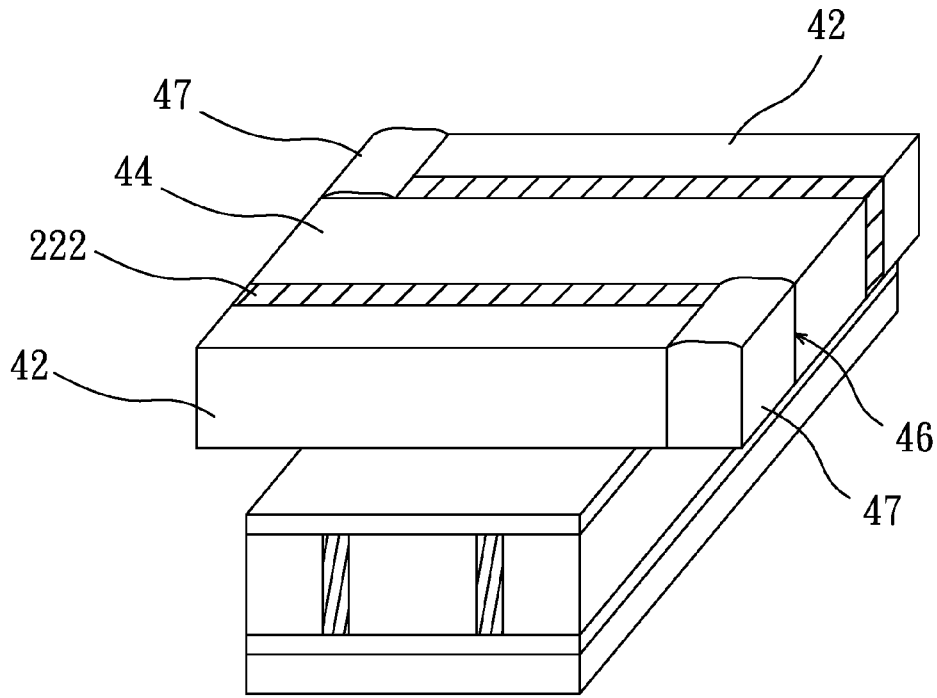


Fig. 4Q

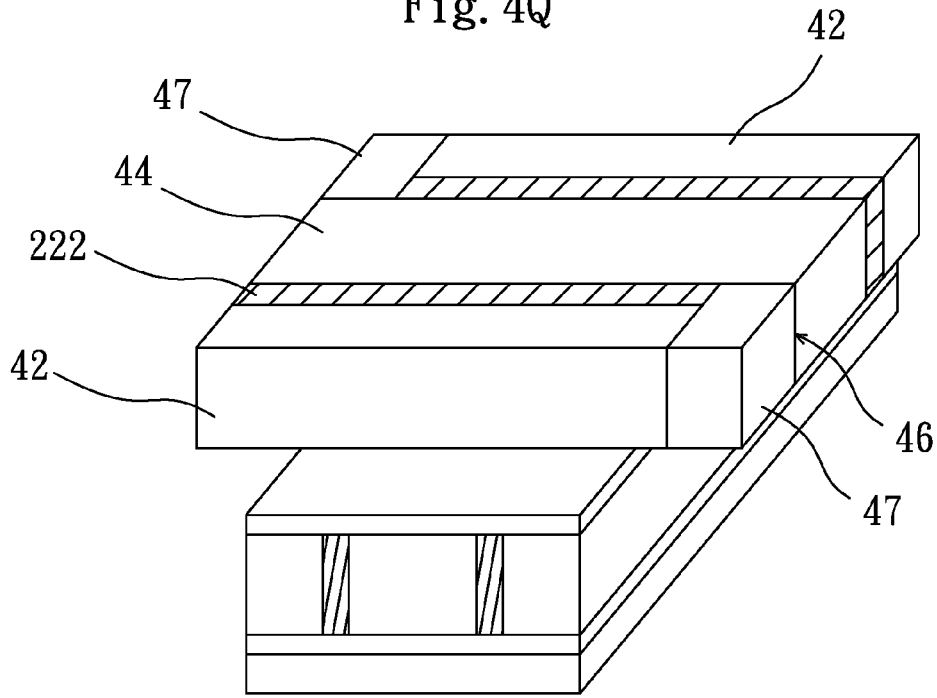


Fig. 4R

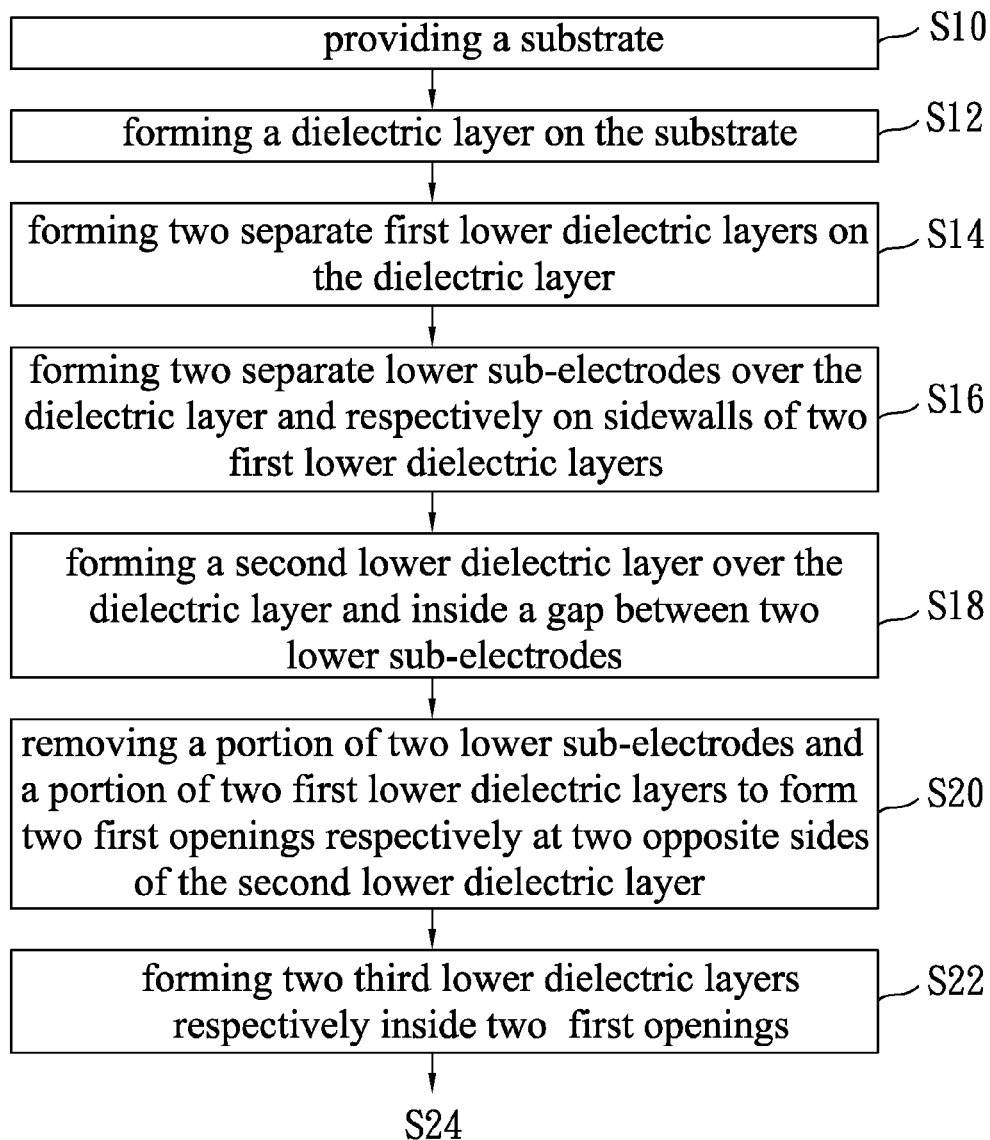


Fig. 5A

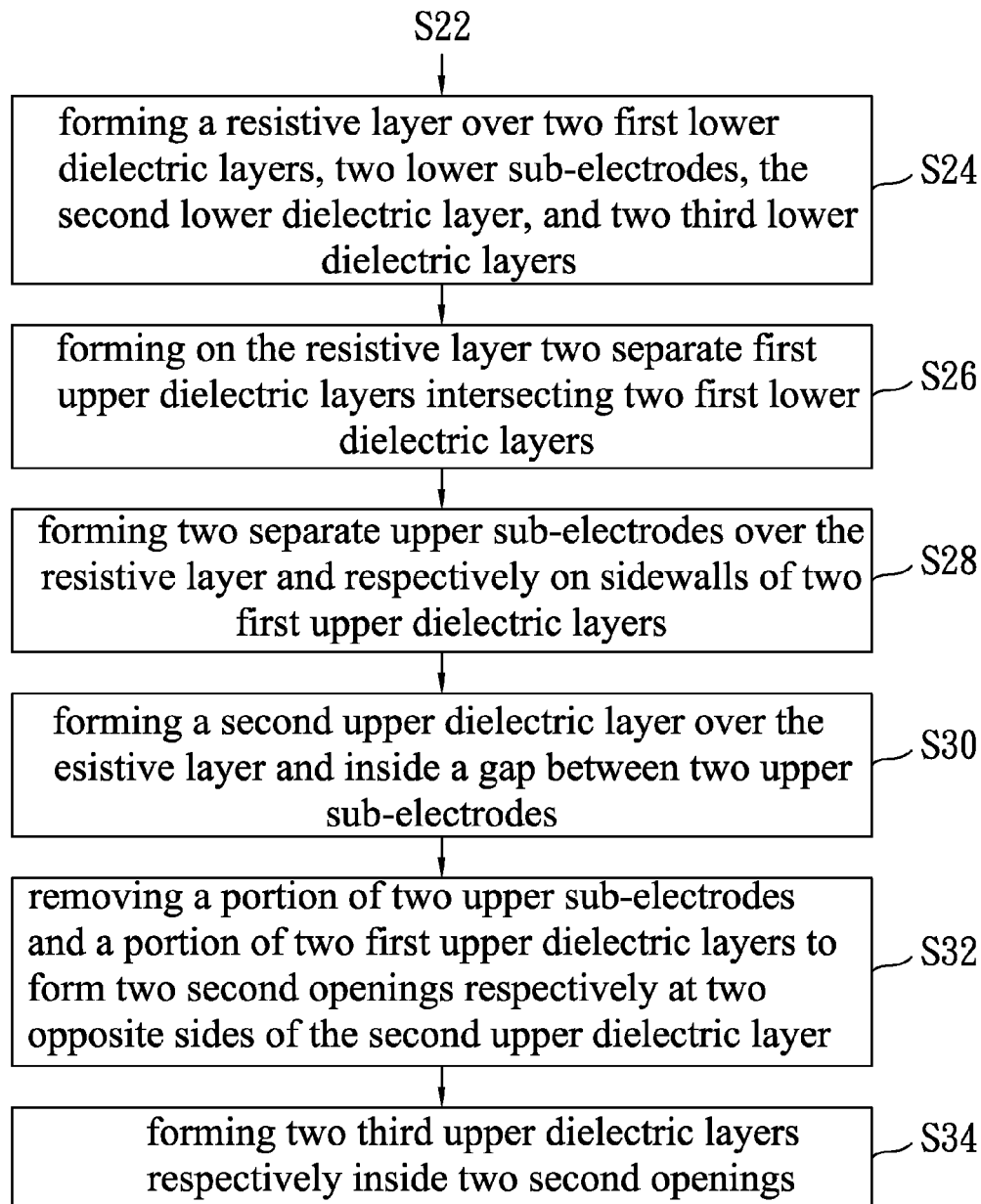


Fig. 5B

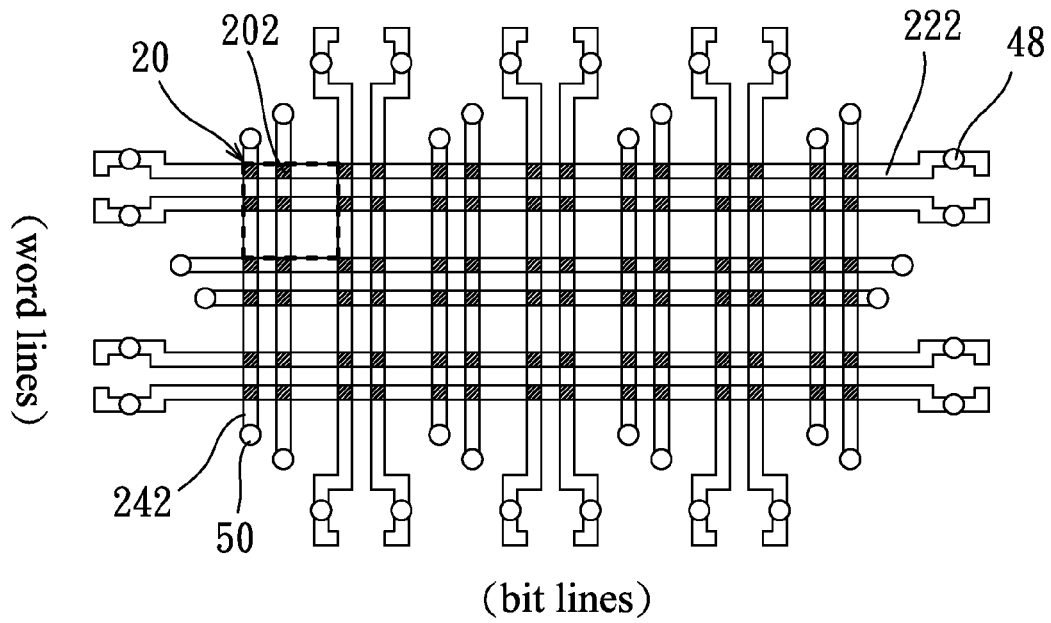


Fig. 6

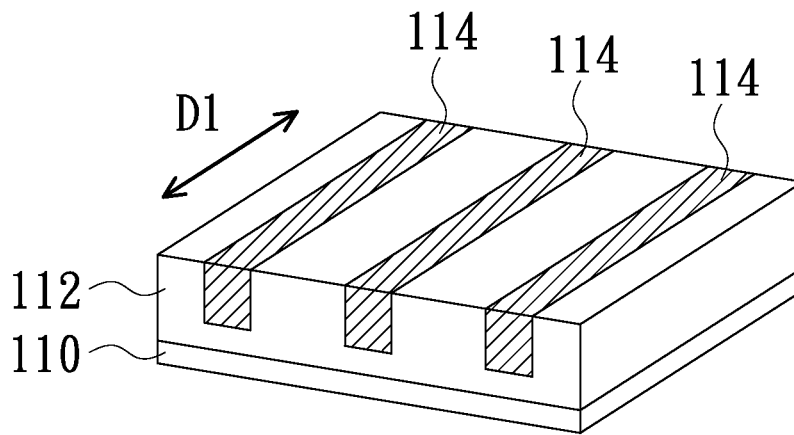


Fig. 7A

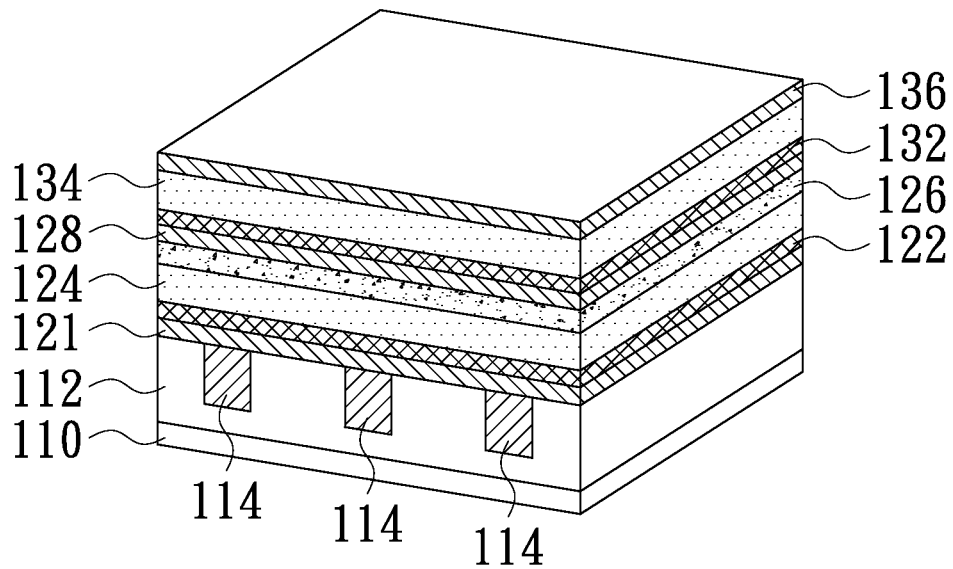


Fig. 7B

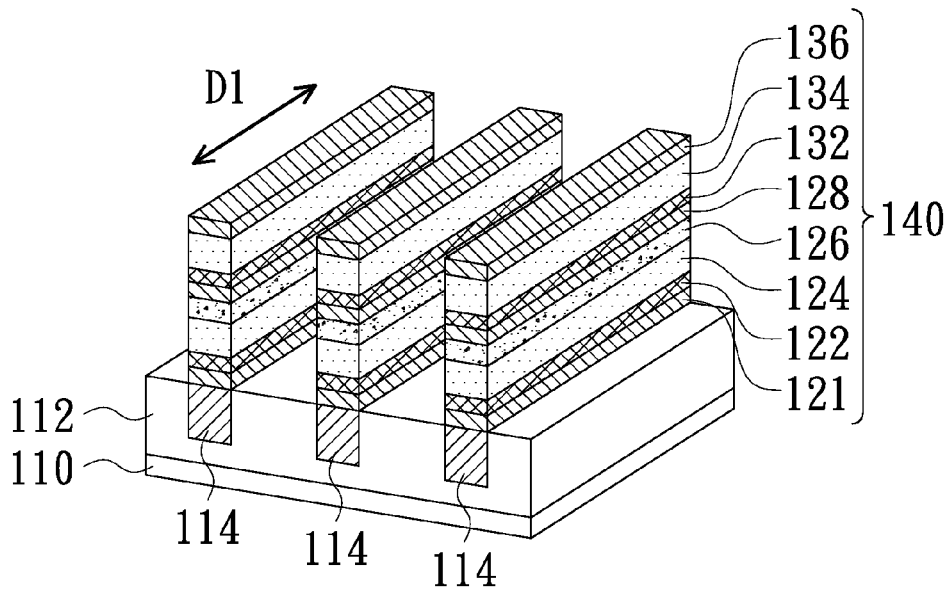


Fig. 7C

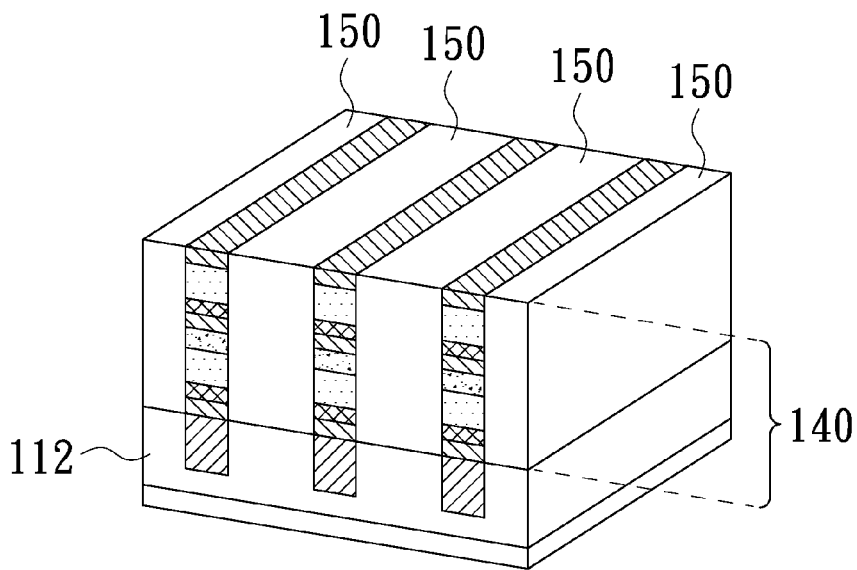


Fig. 7D

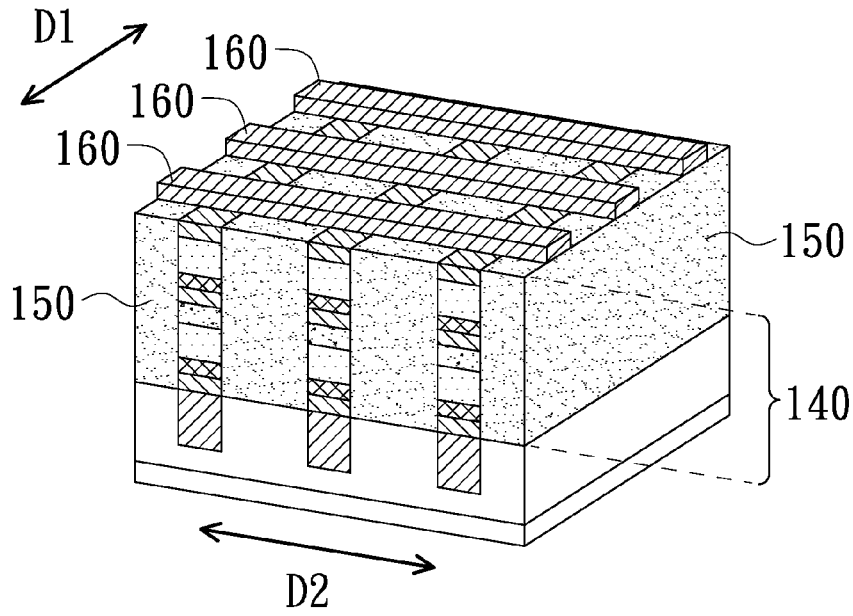


Fig. 7E

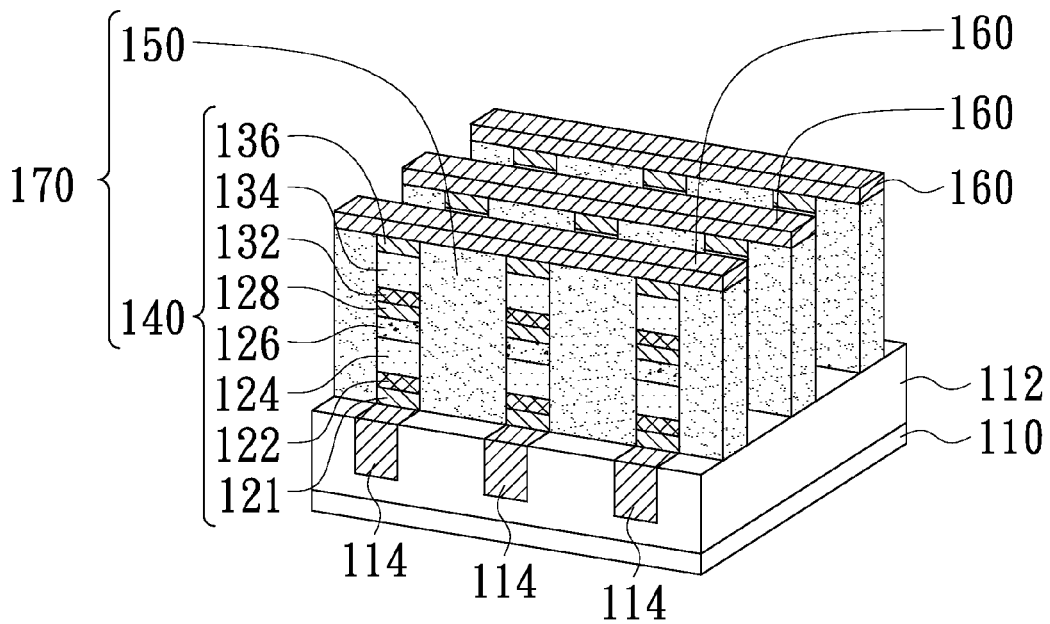


Fig. 7F

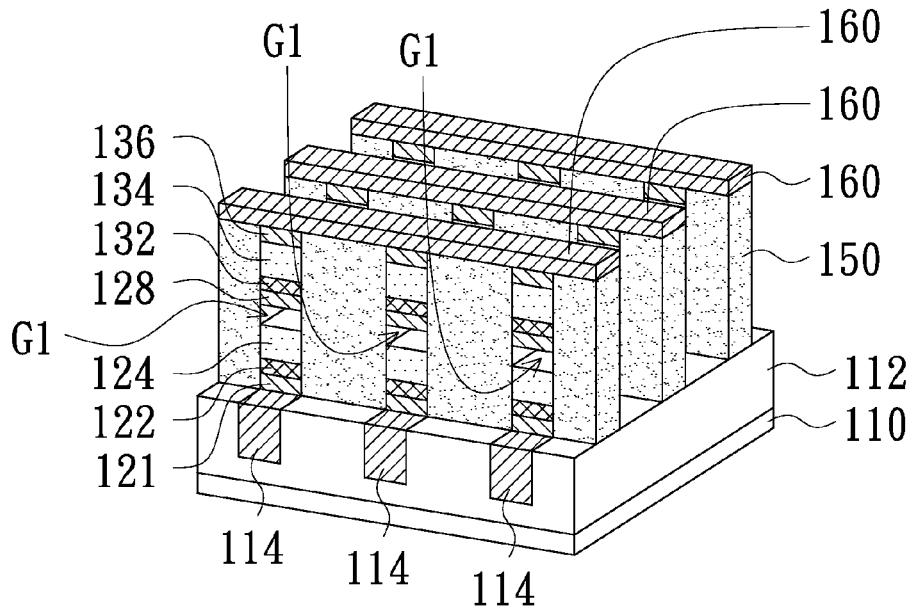


Fig. 7G

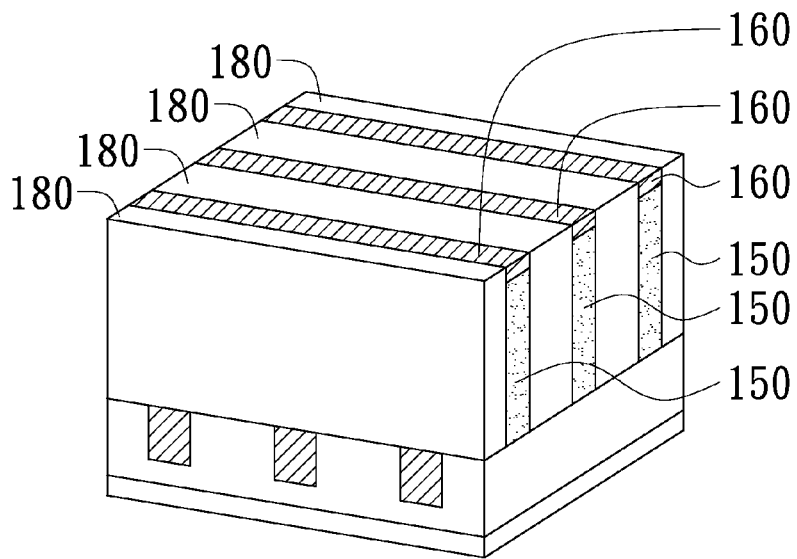


Fig. 7H

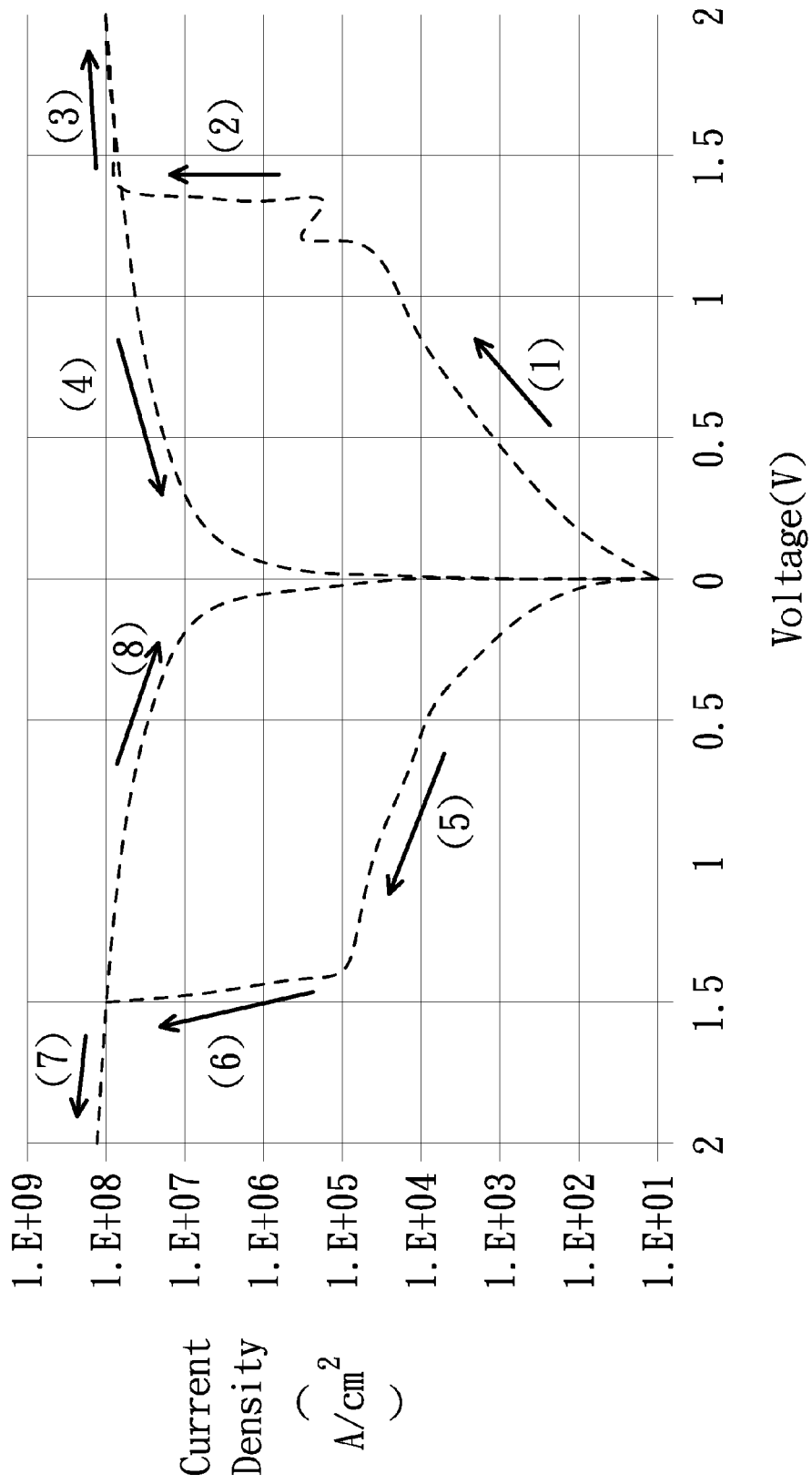


Fig. 8

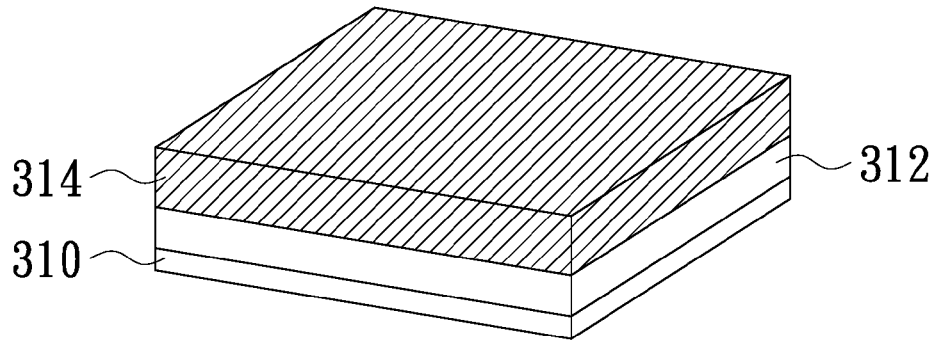


Fig. 9A

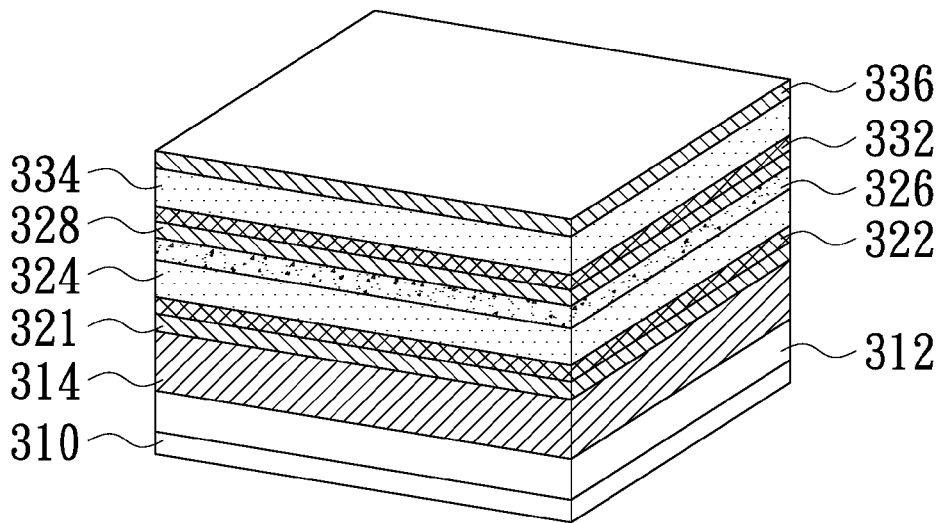


Fig. 9B

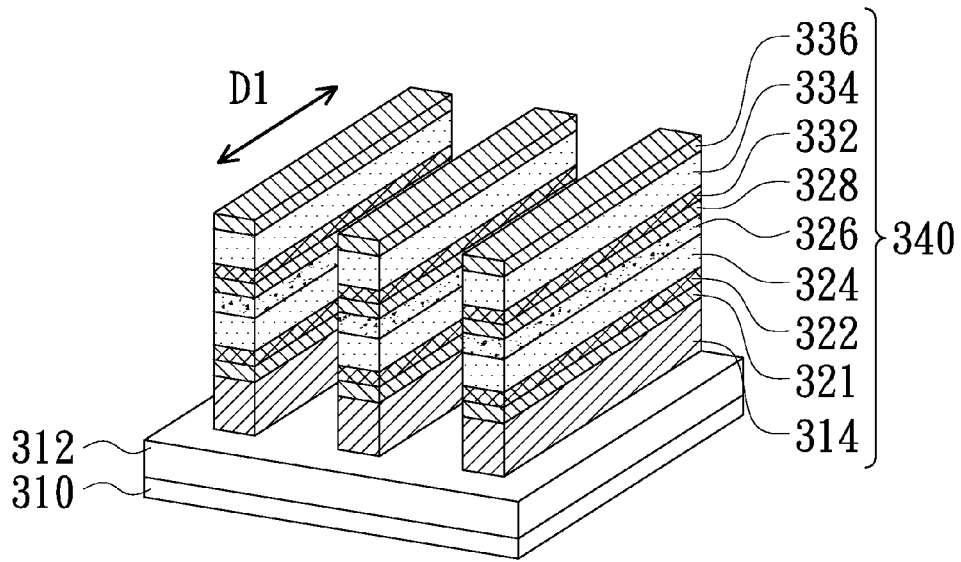


Fig. 9C

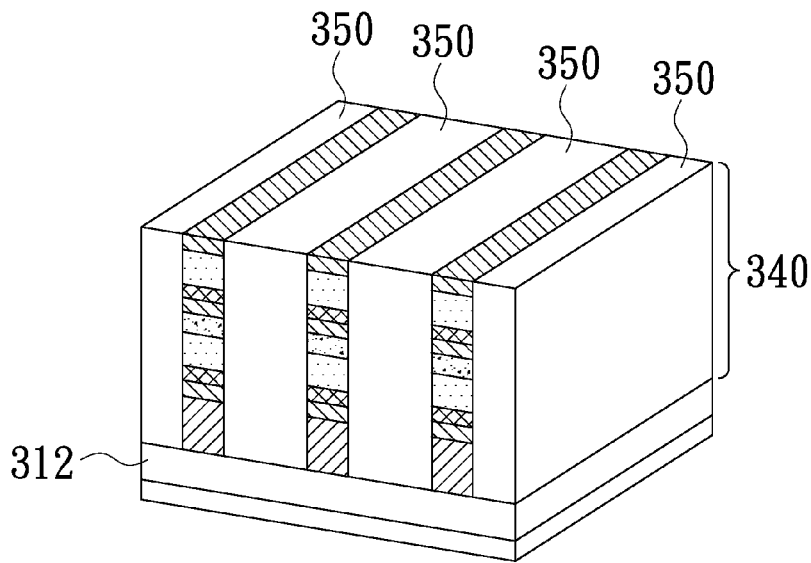


Fig. 9D

SEMICONDUCTOR MEMORY STORAGE ARRAY DEVICE AND METHOD FOR FABRICATING THE SAME

This application is a continuation-in-part (CIP) of U.S. application Ser. No. 13/452,544 filed on Apr. 20, 2012. The entire disclosure of U.S. application Ser. No. 13/452,544 is incorporated herein by reference.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to a memory structure and a method for fabricating the same, particularly to an ultra high density non-volatile memory device having a quadruple memory density in an identical area.

2. Description of the Related Art

Advanced memories are emerging persistently, such as PCRAM (Phase Change Random Access Memory), MRAM (Magnetic Random Access Memory) and RRAM (Resistive Random Access Memory). Featuring high read/write speed, non-destructive reading, durability to extreme temperature, high integration with related circuits, RRAM is regarded as a memory potential to replace all the existing ones.

RRAM also has advantages of high density, low cost, low power consumption, superior data retention ability, and simple structure. Refer to FIG. 1 schematically showing an array structure of a conventional RRAM. The conventional RRAM comprises a plurality of first metal lines **10** functioning as bit lines and a plurality of second metal lines **12** functioning as word lines. The first metal lines **10** intersect the second metal lines **12**. An insulating layer **14** is arranged between the first metal lines **10** and the second metal lines **12**. Thus is formed a memory cell **16** in each intersection of the first metal lines **10** and the second metal lines **12**.

The quantity of the memory cells **16** depends on the quantities of the first metal lines **10** and second metal lines **12**. For example, there are 21 memory cells **16** if there are 7 first metal lines **10** in columns and 3 second metal lines **12** in rows. The principle of RRAM is that a voltage is applied to the first and second metal lines **10** and **12** to transform the insulating layer **14** from a high-resistance state to a low-resistance state or from a low-resistance state to a high-resistance state.

Because of market demand and technical evolution, the size of elements has reduced from microns to nanometers (1-100 nm). Suppose that the minimum feature size is 90 nm and denoted with F. In a conventional RRAM, the first metal line **10** has a width of 1 F, and the spacing between two adjacent first metal lines **10** is also 1 F. Thus, one first metal line **10** and the spacing thereof have a total width of 2 F. The second metal line **12** has a width of 1 F, and the spacing between two adjacent second metal lines **12** is also 1 F. Thus, one second metal line **12** and the spacing thereof also have a total width of 2 F. Therefore, the conventional RRAM has a minimum cell area of 4 F². The scalability of such a memory structure has reached a physical limit. The density of a memory is unlikely to increase except the structures thereof are stacked up vertically. Nevertheless, the stacked memory structure is still hard to meet the demand for a high-capacity small-volume memory. Therefore, how to increase the memory density in a minimum memory area is a problem the manufacturers are eager to overcome.

SUMMARY OF THE INVENTION

The primary objective of the present invention is to provide an ultra high density resistive memory structure and a method

for fabricating the same, wherein a photolithography-etching process is used to divide an electrode into two sub-electrodes to double the quantities of bit lines and word lines, whereby is quadrupled the density of memory cells, and whereby the present invention can use the 90 nm process to fabricate the memory structure having the same capacity as the memory structure fabricated in the 45 nm process, and whereby the density of a memory leaps ahead by two generations.

Another objective of the present invention is to provide an ultra high density resistive memory structure and a method for fabricating the same, wherein the structures of a memory is stacked up vertically to increase the capacity of the memory.

To realize the abovementioned objectives, the present invention proposes an ultra high density resistive memory structure, which comprises a plurality of memory cells. Each memory cell further comprises an upper electrode, a lower electrode, and a resistive layer. The upper electrode includes two separate upper sub-electrodes. The lower electrode includes two separate lower sub-electrodes. The two upper sub-electrodes intersect the two lower sub-electrodes. The resistive layer is arranged between the upper sub-electrodes and the lower sub-electrodes. Thereby, four sub-memory cells are formed in the intersections of the two upper sub-electrodes and the two lower sub-electrodes.

The present invention also proposes a method for fabricating an ultra high density resistive memory structure, which comprises steps: providing a substrate; forming a dielectric layer on the substrate; forming two separate first lower dielectric layers on the dielectric layer with a photolithography-etching process; forming two separate lower sub-electrodes over the dielectric layer and respectively on sidewalls of the two first lower dielectric layers; forming a second lower dielectric layer over the dielectric layer and inside a gap between the two lower sub-electrodes; removing a portion of the two lower sub-electrodes and a portion of the two first lower dielectric layers to form two first openings respectively at two opposite sides of the second lower dielectric layer to make the two lower sub-electrodes independently controlled; forming two third lower dielectric layers respectively inside the two first openings and flattening the two third lower dielectric layers; forming a resistive layer over the two first lower dielectric layers, the two lower sub-electrodes, the second lower dielectric layer, and the two third lower dielectric layers; forming on the resistive layer two separate first upper dielectric layers intersecting the two first lower dielectric layers to present a cross-like shape; forming two separate upper sub-electrodes over the resistive layer and respectively on sidewalls of the two first upper dielectric layers; forming a second upper dielectric layer over the resistive layer and inside a gap between the two upper sub-electrodes; removing a portion of the two upper sub-electrodes and a portion of the two first upper dielectric layers to form two second openings respectively at two opposite sides of the second upper dielectric layer to make the two upper sub-electrodes independently controlled; and forming two third upper dielectric layers respectively inside the two second openings to facilitate the process of stacking memory cells. The present invention quadruples the capacity of a memory structure in the same area, using the 90 nm process to fabricate the upper electrode into two upper sub-electrodes and the lower electrode into two lower sub-electrodes.

In accordance with one aspect, the present invention provides a semiconductor memory storage array device formed on a substrate and the method for fabricating the same, wherein the semiconductor memory storage array device comprises a first electrode layer, an oxide layer, a second

electrode layer, a memory material layer and a first insulator layer. The oxide layer is disposed on the first electrode layer. The second electrode layer is disposed on the oxide layer. The memory material layer is disposed on the second electrode layer. The first insulator layer is disposed adjacent to two sidewalls of the first electrode layer, the oxide layer, the second electrode layer and the memory material layer, so to define a gap either between the first electrode layer and the oxide layer or between the second electrode layer and the oxide layer.

Below, embodiments are described in detail to make easily understood the objectives, technical contents, characteristics and accomplishments of the present invention.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 schematically shows an array structure of a conventional RRAM;

FIG. 2 is a perspective view schematically showing an ultra high density resistive memory structure according to one embodiment of the present invention;

FIG. 3 is a top view schematically showing an ultra high density resistive memory structure according to one embodiment of the present invention;

FIGS. 4A-4R schematically show the steps of a method for fabricating an ultra high density resistive memory structure according to one embodiment of the present invention;

FIG. 5A-5B shows a flowchart of a method for fabricating an ultra high density resistive memory structure according to one embodiment of the present invention;

FIG. 6 schematically shows the external connections of the memory cells according to one embodiment of the present invention.

FIGS. 7A-7H are cross-sectional views of processing structures illustrating a method for fabricating a semiconductor memory storage array device in accordance with one embodiment of the present invention;

FIG. 8 is a diagram illustrating switching characteristics of a TVS selector in accordance with one embodiment of the present invention; and

FIGS. 9A-9D are cross-sectional views illustrating portions of processing structures for fabricating a semiconductor memory storage array device in accordance with another embodiment of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

With emerging portable electronics and persistent function upgrade, the global memory market is also growing fast. Under a situation that the feature size of semiconductor is unlikely to reduce anymore, the Inventors have been devoted to research and development and finally propose an ultra high density resistive memory structure to further increase the capacity of a memory in an identical area, whereby to satisfy the demand for higher capacity memories and meet the trend toward compact and slim products.

Refer to FIG. 2 and FIG. 3 respectively a perspective view and a top view of an ultra high density resistive memory structure according to one embodiment of the present invention. The ultra high density resistive memory structure of the present invention comprises a plurality of memory cells 20. Each memory cell 20 further comprises an upper electrode 22, a lower electrode 24 and a resistive layer 26. In this embodiment, the memory having a feature size of 90 nm is improved to increase the density thereof. The lower electrode 24 has two separate lower sub-electrodes 242. In other words, the original lower electrode 24 having a width of 1 F is

fabricated into two separate lower sub-electrodes 242, and the two lower sub-electrodes 242 and the gap therebetween totally have a width of 1 F. The resistive layer 26 is arranged over the lower electrode 24. The upper electrode 22 is laid over the resistive layer 26 and arranged to intersect the lower electrode 24. The upper electrode 22 has two separate upper sub-electrodes 222. In other words, the original upper electrode 22 having a width of 1 F is fabricated into two separate upper sub-electrodes 222, and the two upper sub-electrodes 222 and the gap therebetween totally have a width of 1 F. The resistive layer 26 is interposed between the upper electrode 22 and the lower electrode 24. Thus, the intersections of the two upper sub-electrodes 222 and the two lower sub-electrodes 242 form four sub-memory cells 202. Therefore, the present invention can fabricate memory cells having an area of 1 F², which is much smaller than 4 F² the area of the memory cells of the conventional RRAM. Refer to FIG. 1 again. The conventional RRAM has 7 first metal lines 10 (the lower electrodes) and 3 second metal lines 12 (the upper electrodes). Thus, the conventional RRAM has 21 memory cells. In the same area of the memory structure of the present invention, the quantity of the lower sub-electrodes 242 is 14, which is the double of the quantity of the first metal lines 10; the quantity of the upper sub-electrodes 222 is 6, which is also the double of the quantity of the second metal lines 12. Thus, the memory structure of the present invention has 84 memory cells 202, which are quadruple the memory cells of the conventional RRAM in the same area. Therefore, the present invention can use the 90 nm process to fabricate the memory structure having the same capacity as the memory structure fabricated in the 45 nm process.

Below is introduced a method for fabricating an ultra high density resistive memory structure of the present invention. Refer to FIGS. 4A-4R and FIG. 5A-5B. FIGS. 4A-4R schematically show the steps of a method for fabricating an ultra high density resistive memory structure according to one embodiment of the present invention. FIG. 5A-5B shows a flowchart of a method for fabricating an ultra high density resistive memory structure according to one embodiment of the present invention. In Step S10, provide a substrate 30, such as a substrate made of silicon. In Step S12, form a dielectric layer 32 (such as a dielectric layer made of silicon dioxide (SiO₂)) on the substrate 30, as shown in FIG. 4A. In Step S14, form a complete layer of a first lower dielectric layer 34 (made of such as silicon nitride (SiN)) on the dielectric layer 32, as shown in FIG. 4B; next, use a photolithography-etching process to form a trench 342 in the middle of the first lower dielectric layer 34 to generate two separate first lower dielectric layers 34 on the dielectric layer 32, as shown in FIG. 4C. In Step S16, form a complete layer of a lower electrode 24 over the first lower dielectric layer 34 and the dielectric layer 32 inside the trench 342 with a CVD (Chemical Vapor Deposition) method, a PVD (Physical Vapor Deposition) method, or an ALD (Atomic Layer Deposition) method, as shown in FIG. 4D; next, use an RIE (Reactive Ion Etching) process and one of chlorine, argon and hydrogen bromide to remove the lower electrode 24 on the first lower dielectric layer 34 and a portion of the lower electrode 24 inside the trench 342 to form two separate lower sub-electrodes 242 above the dielectric layer 32 and respectively on two sidewalls of two separate first lower dielectric layers 34, as shown in FIG. 4E. The preferred width of the lower sub-electrode 24 is 1-10 nm.

In Step S18, use a CVD method to form a second lower dielectric layer 36 over the dielectric layer 32 inside the gap between the two separate lower sub-electrodes 242. The second lower dielectric layer 36 is made of silicon dioxide or

silicon nitride. As shown in FIG. 4F, the as-deposited second lower dielectric layer 36 is rugged. Therefore, a CMP (Chemical Mechanical Polishing) method is used to flatten the as-deposited second lower dielectric layer 36 and make the top of the second lower dielectric layer 36 and the top of two lower sub-electrodes 242 on the same plane, as shown in FIG. 4G. In Step S20, use a photolithographic process (such as a photomask process) and an etching process (such as an RIE process) to remove a portion of two lower sub-electrodes 242 and a portion of two first lower dielectric layers 34 to form two first openings 38 respectively at two opposite sides of the second lower dielectric layer 36, as shown in FIG. 4H. Thereby, the two lower sub-electrodes 242 are disconnected electrically and can be controlled independently. The description of the abovementioned steps demonstrates that the present invention can fabricate two lower sub-electrodes 242 in a dimension of 1 F.

In Step S22, form two third lower dielectric layers 40 inside the two first openings 38, as shown in FIG. 4I. The third lower dielectric layers 40 are made of nitride or oxide. Similarly, the third lower dielectric layers 40 are flattened with a CMP method, as shown in FIG. 4J. In Step S24, form a resistive layer 26 over two first lower dielectric layers 34, two lower sub-electrodes 242, the second lower dielectric layer 36, and two third lower dielectric layers 40, as shown in FIG. 4K. The resistive layer 26 is made of a material selected from a group consisting of tungsten oxide (WO_x), hafnium oxide (HfO_x), titanium oxide (TiO_x), nickel oxide (NiO_x), aluminum oxide (AlO_x), zirconium oxide (ZrO_x), zinc oxide (ZnO_x), and copper oxide (CuO_x).

Next, an upper electrode 22 will be fabricated in the same way as the lower electrode 24. Note that the lower electrode 24 is arranged in the X-axis direction and the upper electrode 22 is arranged in the Y-axis direction. In other words, the upper electrode 22 intersects the lower electrode 24. In Step S26, form on the resistive layer 26 a complete layer of a first upper dielectric layer 42 (such a dielectric layer made of silicon nitride (SiN)), and use a photolithography-etching process to form a trench 422 in the middle of the first upper dielectric layer 42, whereby are generated two separate first upper dielectric layers 42 on the resistive layer 26, as shown in FIG. 4L. In Step S28, form a complete layer of an upper electrode 22 over the first upper dielectric layer 42 and the resistive layer 26 (including the resistive layer 26 inside the trench 422) with a CVD, PVD, or ALD method; use an RIE process together with chlorine, argon or hydrogen bromide to remove the upper electrode 22 on the first upper dielectric layer 22 and remove a portion of the upper electrode 22 inside the trench 422 to form two separate upper sub-electrodes 222 respectively on two sidewalls of the two separate first upper dielectric layers 42, as shown in FIG. 4M. The preferred width of the upper sub-electrode 222 is 1-10 nm. In Step S30, use a CVD method to form a second upper dielectric layer 44 over the resistive layer 26 inside the gap between the two upper sub-electrodes 222, as shown in FIG. 4N. The second upper dielectric layer 44 is made of silicon dioxide or silicon nitride. As shown in FIG. 4N, the as-deposited second upper dielectric layer 44 is rugged. Therefore, a CMP (Chemical Mechanical Polishing) method is used to flatten the as-deposited second upper dielectric layer 44 and make the top of the second upper dielectric layer 44 and the top of two upper sub-electrodes 222 on the same plane, as shown in FIG. 4O. In Step S32, use a photolithography-etching process to remove a portion of the two upper sub-electrodes 222 and a portion of the first upper dielectric layers 42 to form two second openings 46 respectively at two opposite ends of the second upper dielectric layers 44, as shown in FIG. 4P. Thereby, the two

upper sub-electrodes 222 are disconnected electrically and can be controlled independently. The description of the abovementioned steps demonstrates that the present invention can fabricate two upper sub-electrodes 222 in a dimension of 1 F.

Via the abovementioned method, the original lower electrode 24 is fabricated into two lower sub-electrodes 242, and the original upper electrode 22 is fabricated into two upper sub-electrodes 222, whereby the capacity of a memory is quadrupled in an identical area. In Step S34, form two third upper dielectric layers 47 inside the two second openings 46, as shown in FIG. 4Q. The third upper dielectric layers 47 are made of nitride or oxide. Similarly, the third upper dielectric layers 47 are flattened with a CMP method, as shown in FIG. 4R. Step S12-Step S32 may be repeated to stack memory cells and increase memory capacity.

Refer to FIG. 3 and FIG. 6. FIG. 6 schematically shows the external connections of the memory cells. The two upper sub-electrodes 222 of each memory cell 20 function as word lines and respectively connect with upper electric contacts 48. Pairs of the upper electric contacts 48 are arranged intermittently. The two lower sub-electrodes 242 of each memory cell 20 function as bit lines and respectively connect with lower electric contacts 50. Pairs of the lower electric contacts 50 are arranged intermittently, too. Thus is effectively utilized the external connection area of the word lines and bit lines and achieved the optimal design of the sub-memory cells 202 and the ultra high density of the memory.

The embodiments described above are only to exemplify the present invention but not to limit the scope of the present invention. Any equivalent modification or variation according to the characteristics of spirit of the present invention is to be also included within the scope of the present invention.

FIGS. 7A-7H are cross-sectional views of processing structures illustrating a method for fabricating a semiconductor memory storage array device in accordance with one embodiment of the present invention, wherein the method comprises several steps as follows: Referring to FIG. 7A, a substrate 110 comprising a zeroth insulator layer 112 and a plurality of zeroth signal lines 114 extending along a first direction D1 is firstly provided, wherein the zeroth insulator layer 112 is formed on the substrate 110; the signal lines 114 are formed in the zeroth insulator layer 112; and the signal lines 114 are separated from each other by the zeroth insulator layer 112. In the present embodiment, the signal lines 114 may function as word lines of the semiconductor memory storage array device.

Referring to FIG. 7B, a buffer layer 121, a first electrode layer 122, an oxide layer 124, a sacrifice layer 126, a second electrode layer 128, a third electrode 132, a memory material layer 134 and a fourth electrode layer 136 are formed in a manner of sequentially stacked on the zeroth insulator layer 112 and the signal lines 114, wherein the sacrifice layer 126 may be formed either between the first electrode layer 122 and the oxide layer 124 or between the second electrode layer 128 and the oxide layer 124. In other words, the arrangement of the sacrifice layer 126 that is disposed between the oxide layer 124 and the second electrode layer 128, as depicted in the FIG. 7B, is just illustrative, but not used to limit the scope of the present invention. In some other embodiments, the sacrifice layer 126 may be disposed between the first electrode layer 122 and the oxide layer 124.

The buffer layer 121 is an optional interface layer used to prevent the first electrode layer 122 from being peeled off from the zeroth insulator layer 112 and the signal lines 114. A processor can determine whether or not to form the buffer layer 121 according to a binding force that is needed to fix the

first electrode layer **122** on the zeroth insulator layer **112** as well as the signal lines **114** securely. In one preferred embodiment of the present invention, the first electrode layer **122** is made of tungsten (W), the buffer layer **121**, meanwhile, may be made of, but not limited to, titanium nitride (TiN), titanium (Ti), tantalum (Ta) or tantalum nitride (TaN). The oxide layer **124** is made of materials selected from a group consisting of tungsten oxide (WO_x), hafnium oxide (HfO_x), titanium oxide (TiO_x), nitric oxide (NiO_x), aluminium oxide (AlO_x), zirconium oxide (ZrO_x), zinc oxide (ZnO_x) and copper oxide (CuO_x). The memory material layer **134** may be a phase change random access memory (PCRAM) layer, a magnetoresistive random access memory (MRAM) layer or a resistive random access memory (RRAM) layer, wherein the PCRAM layer is made of (Ge₂Sb₂Te₅); the MRAM layer comprises a Fe/MgOx/Fe multilayer structure; and the RRAM layer is made of material selected from a group consisting of WO_x, HfO_x, TiO_x, NiO_x, AlO_x, ZrO_x, ZnO_x and CuO_x. For convenience purpose, hereinafter the material layer **134** may be presented as a RRAM layer. In other words the memory elements of the semiconductor memory array device may be presented as RRAM elements. However, the following embodiments are just illustrative but not used to limit the scope of the present invention. Other kinds of memory element may be also applied in the embodiments of the present invention.

The sacrifice layer **126** is made of silicon oxide (SiO_x) or silicon nitride (SiN), and the third electrode layer **132** is made of W. It is worthy to note that since the second electrode layer **128** that is disposed between the sacrifice layer **126** and the third electrode layer **132** is made of TiN, Ti, Ta or TaN, thus while the third electrode layer **132** is made of W, the second electrode layer **128** can function as a buffer layer used to prevent the third electrode layer **132** from being peeled off from the sacrifice layer **126** and to improve the process reliability. Similarly, the aforementioned materials used to form the sacrifice layer **126**, the second electrode layer **128** and the third electrode layer **132** are just illustrative, and other suitable materials can be also applied.

Referring to FIGS. 7B and 7C, an etching process is next performed to remove portions of the buffer layer **121**, the first electrode layer **122**, the oxide layer **124**, the sacrifice layer **126**, the second electrode layer **128**, the third electrode layer **132**, the memory material layer **134** and the fourth electrode **136** to define a plurality of zeroth structures **140**, wherein each of the zeroth structures **140** is disposed over one of the zeroth signal lines **114** and extending along the first direction D1. In the present embodiment, each of the zeroth structures **140** shapes as a long column composed by strip portions of the remaining buffer layer **121**, the remaining first electrode layer **122**, the remaining oxide layer **124**, the remaining sacrifice layer **126**, the remaining second electrode layer **128**, the remaining third electrode layer **132**, the memory material layer **134** and the fourth electrode layer **136**.

Referring to FIGS. 7D and 7E, after the zeroth structures **140** are defined, a first insulator layer **150** is then formed on the zeroth buffer layer **112** to fill the slit trenches defined by two adjacent zeroth structures **140** (see FIG. 7D). Subsequently, a plurality of second signal lines **160** extending along a second direction D2 are formed on the first insulator layer **150** and the zeroth structures **140**, wherein the second direction D2 and the first direction D1 form a right angle (see FIG. 7E). However, in some other embodiment, the angle formed by the second direction D2 and the first direction D1 is not limited to 90°. In some embodiments of the present invention, the first insulator layer **150** and the zeroth buffer layer **112**

may consist of identical material. The second signal lines **160** may function as the word lines of the semiconductor memory storage array device.

Referring to FIGS. 7F and 7G, another etching process using the second signal lines **160** as the mask is subsequently performed to remove portions of the first insulator layer **150** and the zeroth structures **140**, so as to form a plurality of first structures **170** lying beneath the second signal lines **160**. In the present embodiment, each of the first structures **170** shapes as a long column composed by portions of the remaining first insulator layer **150** and the remaining zeroth structures **140**, wherein the remaining zeroth structures **140** may shape as pillars composed by portions of the remaining buffer layer **121**, the remaining first electrode layer **122**, the remaining oxide layer **124**, the remaining sacrifice layer **126**, the remaining second electrode layer **128**, the remaining third electrode layer **132** and the remaining fourth electrode **134**. Accordingly two ends of the sacrifice later **126** can be exposed from the trenches formed by the etching process and used to defined the long column of the structure **170** (see FIG. 7F). Yet another etching process is then performed to remove the remaining sacrifice layer **126**, whereby a gap G1 defined by the remaining portions of the oxide layer **124**, the second electrode layer **128** and the first insulator layer **150** can be formed in each of the pillars (see FIG. 7F). It is worthy to note that because the sacrifices layer **126** and the first insulator layer **150** are both dielectric layers, the material used to form the first insulator layer **150** is preferably different from the material consisting of the sacrifices layer **126** to prevent the first insulator layer **150** being removed by the etching process for forming the gap G1. In addition, the etching process necessitates a proper selectability to only remove the sacrifices layer **126** instead of damaging the first insulator layer **150**. For example, on the one hand, when the sacrifices layer **126** is made of SiN, and the material consisting of the first insulator layer **150** can be SiO_x; a phosphoric acid based etching process may be applied to remove the sacrifices layer **126**. On the other hand, when the sacrifices layer **126** is made of SiO_x, and the material consisting of the first insulator layer **150** is SiN; an etching process comprising hydrofluoric acid (HF) and buffer oxide etcher (BOE) may be applied to remove the sacrifices layer **126**. In a preferred embodiment of the present invention, the sacrifices layer **126** has a thickness about 10 angstrom (Å), thus the gap G1 that is formed by removing the sacrifices layer **126** may have a height calculated from the oxide layer **124** to the second electrode layer **128** substantially equal to or less than 10 Å. Besides, if the sacrifices layer **126** is alternatively formed between the oxide layer **124** and the first electrode layer **122**, the gap G1 should be defined by the first insulator layer **150**, the oxide layer **124** and the first electrode layer **122**.

Referring to FIG. 7G, the semiconductor memory storage array device formed by the aforementioned method comprises a substrate **110**, a zeroth isolator layer **112**, a plurality of zeroth signal lines **114**, a buffer layer **121**, a first electrode layer **122**, an oxide layer **124**, a Gap G1, a second electrode layer **128**, a third electrode layer **132**, a memory material layer **134**, a fourth electrode layer **136**, a plurality of first signal lines **160** and a first isolator layer **150**. The zeroth isolator layer **112** is disposed on the substrate **110**. The zeroth signal lines **114** are disposed in the zeroth isolator layer **112** extending along a first direction D1, and each of the zeroth signal lines **114** is separated by the zeroth isolator layer **112**. The buffer layer **121**, the first electrode layer **122**, the oxide layer **124**, the second electrode layer **128**, the third electrode layer **132**, the memory material layer **134** and the fourth electrode layer **136** are sequentially stacked on the zeroth

signal lines **114** to form a plurality of pillar structures. The first isolator layer **150** is disposed on the zeroth isolator layer **112** and adjacent to two sidewalls of each pillar structures in a manner of staggering the pillar structures. The first signal lines **160** is disposed on the first isolator layer **150** and the plurality of pillar structures and extends along a second direction **D2** to overlap the zeroth signal lines **114**, wherein the pillar structures are disposed within the overlapped areas identified by the zeroth signal lines **114** and the first signal lines **160**. The gap **G1** is defined by the second electrode layer **128**, the oxide layer **124** and the first isolator layer **150**. However, in some other embodiments, the gap **G1** may be defined by the first electrode layer **122**, the oxide layer **124** and the first isolator layer **150**. In other words, the gap **G1** may be formed either between the second electrode layer **128** and the oxide layer **124** or between the first electrode layer **122** and the oxide layer **124**.

Functionally, the first electrode layer **122**, the oxide layer **124**, the second electrode layer **128** and the gap **G1** formed there among may compose a threshold vacuum switch (TVS), and the third electrode layer **132**, the memory material layer **134** and the fourth electrode layer **136** may compose a RRAM element. Accordingly, in the embodiments of the present invention, the TVS connected to the RRAM element in series may function as a selector of the semiconductor memory storage array device. In some embodiments, a vacuum is created in the gap **G1**. However, in other embodiment, the gap **G1** is alternatively filled with air. In other words, the state of the gap **G1** is conditional upon the arrangements of the subsequent process for fabricating the semiconductor memory storage array device. For example, subsequent processes for forming one or more additional films on the first signal lines **160** may be continued after the processes for forming the structure depicted in FIG. 7G is carried out, a vacuum is created in the gap **G1**, because the vacuum constant in the gap **G1** is always kept identical with the process environment. Typically, a second insulator layer **180** may be formed to fill the trenches used to defined the first signal lines **160** and the first structure **170** (see FIG. 7H) before the subsequent processes for forming the additional films are carried out. In order to prevent the gap **G1** from being filled by the second insulator layer **180**, the second insulator layer **180** is preferably formed by a high density plasma chemical vapor deposition (HDCVD) process or an E-Gun evaporating process. And a confined space may be defined by the second electrode layer **128**, the oxide layer **124**, the first insulator layer **150** and the second insulator layer **180**, after the second insulator layer **180** is formed to block the two ends of the gap **G1**. In some embodiments of the present invention, the first insulator layer **150** and the second insulator layer **180** may be made of identical material.

In the embodiments of the present invention, the TVS composed by the first electrode layer **122**, the oxide layer **124**, the second electrode layer **128** and the gap **G1** is connected to the RRAM element composed by the third electrode layer **132**, the memory material layer **134** and the fourth electrode layer **136** in series. Typically, an RRAM element comprises a memory material layer (such as the memory material layer **134**) made of metal oxide or transition metal oxide with a high resistance state, when a positive bias voltage is imposed onto the RRAM element the resistance state of the memory material layer may be changed from high to low; and the resistance state of the memory material layer may remain at low even if it is not constantly supplied with electric power, whereby the RRAM element can retain the programmed information permanently to implement so called "non-volatile storage". Alternatively, when a negative bias voltage is imposed onto

the RRAM element, the resistance state of the memory material layer may return to high, so as to erase the programmed information. The physical structure and materials of the TVS are similar to that of the RRAM element except the existence of the gap **G1**. Theoretically, the operation mechanism of the TVS would similar to that of the RRAM element. However, if the gap **G1** is taken into account, the low resistance state of the memory material layer (the oxide layer **124**) may return to high, instead of remaining at low, while it is not constantly supplied with electric power. The non-volatile characteristic of the oxide layer **124** is no longer valid. Practically, the TVS electrically connected to the RRAM element in series functions as a selector of the RRAM element. When a positive bias voltage is imposed onto the TVS, the TVS could be turn on due to tunnel electrons passing through the gap **G1**; and turn off while it is not constantly supplied with electric power. However, it should be appreciated that the TVS is not limited to be connected with the RRAM to form a non-volatile memory device and serving as a selector thereof. In some embodiment, the TVS element may be connected to a PCRAM element or a MRAM element in series to form a non-volatile memory device and serving as a selector thereof.

It worthy to note that, in the preferred embodiment, the height of the gap **G1** calculated from the electrode layer, either the first electrode layer **122** or the second electrode layer **128**, to the oxide layer **124** should be limited equal to or less than 10 \AA to allow tunnel electrons passing through, while the electrode layer consists of TiN, and the material of the electrode layer (either the first electrode layer **122** or the second electrode layer **128**) that is associated with the oxide layer **124** and the insulator layer **150** to form the gap **G1** is made of TiN.

FIG. 8 is a diagram illustrating switching characteristics of the TVS selector, wherein the X axle indicates the voltage and the Y axle indicates the current density; the numbered arrows **1-3**, **4**, **5-7** and **8** represent the current density under the conditions while the TVS selector is subjected to a positive bias voltage, no positive bias voltage is constantly supplied, the TVS selector is subjected to a negative bias voltage and no negative bias voltage is constantly supplied respectively. According to FIG. 8, when the bias voltage (for example, about ± 1 volt) imposed on the TVS selector is less than the threshold voltage of the TVS, on the one hand, the current density is measured about 10^4 A/cm^2 . On the other hand, when the bias voltage (for example, about ± 2 volt) imposed on the TVS selector is greater than the threshold voltage of the TVS, the current density is measured about 10^8 A/cm^2 . In comparison with the conventional selectors, the TVS selector of the present invention provides greater current density to the RRAM element. It is suggested that the leaking current and the sneak current problems may be improved by the TVS selector of the present invention.

FIGS. 9A-9D are cross-sectional views illustrating portions of the processing structures for fabricating a semiconductor memory storage array device in accordance with another embodiment of the present invention, wherein the method comprises several steps as follows: Referring to FIG. 9A, a substrate **310** is firstly provided, and a zeroth isolator layer **312** and a zeroth signal layer **314** are sequentially formed on the substrate **310**. Next, a buffer layer **321**, a first electrode layer **322**, an oxide layer **324**, a sacrifice layer **326**, a second electrode layer **328**, a third electrode **332**, a memory material layer **334** and a fourth electrode layer **336** are formed and sequentially stacked on the zeroth signal layer **314** (as shown in FIG. 9B). Since the arrangements of the sacrifice layer **326** and the materials for forming the buffer layer **321**, the first electrode layer **322**, the oxide layer **324**, the sacrifice

layer 326, the second electrode layer 328, the third electrode 332, the memory material layer 334 and the fourth electrode layer 336 are similar to that of the aforementioned embodiments, thus the detailed steps and materials for fabricating the same are not redundantly described.

Referring to FIGS. 9C and 9D, an etching process is then performed to remove portions of the zeroth signal layer 314, the buffer layer 321, the first electrode layer 322, the oxide layer 324, the sacrifice layer 326, the second electrode layer 328, the third electrode layer 332, the memory material layer 334 and the fourth electrode 336 to define a plurality of zeroth structures 340, wherein each of the zeroth structures 340 is disposed over the zeroth insulator layer 312 and extending along the first direction D1 (as shown in FIG. 9D). In the present embodiment, each of the zeroth structures 340 shapes as a long column composed by strip portions of the remaining zeroth signal layer 314, the remaining buffer layer 321, the remaining first electrode layer 322, the remaining oxide layer 324, the remaining sacrifice layer 326, the remaining second electrode layer 328, the remaining third electrode layer 332, the remaining memory material layer 334 and the remaining fourth electrode 336, wherein the remaining portions of the zeroth signal layer 314 may function as word lines of the semiconductor memory storage array device. After the zeroth structures 340 are defined, a first insulator layer 350 is then formed on the zeroth buffer layer 312 to fill the slit trenches defined by two adjacent zeroth structures 340 (see FIG. 9D). Since the subsequent processes for fabricating the semiconductor memory storage array device are identical to that depicted in the FIGS. 7E to 7H, thus they are not redundantly described.

It is worthy to note that since the word lines (the remaining zeroth signal layer 314) and the zeroth structures 340 composed by strip portions of the remaining buffer layer 321, the remaining first electrode layer 322, the remaining oxide layer 324, the remaining sacrifice layer 326, the remaining second electrode layer 328, the remaining third electrode layer 332, the remaining memory material layer 334 and the remaining fourth electrode 336 are formed by the same etching process, thus the separate lithographic step for forming the word lines can be saved, and the zeroth structures 340 can align the word lines more accurately, in comparison with the processes depicted in FIGS. 7A to 7D. In other words, the yield of the processes depicted in FIGS. 9A to 9D can be greater than that depicted in FIGS. 7A to 7D.

In accordance with the aforementioned embodiments of the present invention, a multilayer structure comprising a first electrode layer, an oxide layer and a second electrode layer stacked in sequence as well as a gap defined either between the first electrode layer and the oxide layer or between the second electrode layer and the oxide layer is provided serving as a threshold voltage vacuum switch connected with a memory element of a RRAM device in series to provide the memory element a current density greater than 10^8 A/cm² that is significantly greater than that provided by a convention selector applied by the RRAM, thereby problems of current leakage resulted from the critical feature size shrinkage of the

RRAM device can be avoided. In addition, since the material consisting of the threshold voltage vacuum switch is compatible with the remaining process for forming the semiconductor memory storage array device, thus contaminations resulted from the process for fabricating the threshold voltage vacuum switch can be avoided and the yield of the semiconductor memory storage array device can be increased.

While the invention has been described in terms of what is presently considered to be the most practical and preferred embodiments, it is to be understood that the invention needs not be limited to the disclosed embodiment. On the contrary, it is intended to cover various modifications and similar arrangements included within the spirit and scope of the appended claims which are to be accorded with the broadest interpretation so as to encompass all such modifications and similar structures.

What is claimed is:

1. A semiconductor memory storage array device formed on a substrate comprising:
 - a memory cell, comprising:
 - a first electrode layer;
 - an oxide layer above the first electrode layer;
 - a gap directly above the oxide layer;
 - a second electrode layer directly above the gap and a memory material layer, disposed on the second electrode layer;
 - a first insulator layer, disposed adjacent to a first sidewall of the memory cell; and
 - second insulator layer, disposed adjacent to a second sidewall of the memory cell;
 - wherein the gap is defined by the second electrode layer, the oxide layer, the first insulator layer and the second insulator layer.
2. The semiconductor memory storage array device according to claim 1, wherein the gap has a height about 10 angstrom (Å).
3. The semiconductor memory storage array device according to claim 1, wherein the oxide layer is made of metal oxide or transition metal oxide.
4. The semiconductor memory storage array device according to claim 1, wherein the memory material layer is a PCRAM layer, aMRAM layer or a RRAM layer.
5. The semiconductor memory storage array device according to claim 1, wherein the semiconductor memory storage array device comprising a threshold voltage vacuum switch is used for providing a current density greater than 10^8 A/cm².
6. The semiconductor memory storage array device according to claim 1, further comprising a buffer layer, disposed between the substrate and the first electrode layer.
7. The semiconductor memory storage array device according to claim 6, further comprising:
 - a signal line, disposed between the buffer layer and the substrate; and
 - the first insulator layer and the second insulator layer disposed between the substrate and the signal line.

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